Proposed ISCAS 2026 OC:

General Co-Chairs:

* Yong Lian, York University, Canada, [plian@yorku.ca](mailto:plian@yorku.ca)
* Shao-Jun Wei, Tsinghua University, China, [wsj@tsinghua.edu.cn](mailto:wsj@tsinghua.edu.cn)
* CAS appointed representative

TPC Co-Chairs

* Guoxing Wang, Shanghai Jiao Tong University, China, [guoxing@sjtu.edu.cn](mailto:guoxing@sjtu.edu.cn)
* Eduard Alarcon, UPC Barcelona Tech, Spain, [eduard.alarcon@upc.edu](mailto:eduard.alarcon@upc.edu)
* CAS appointed representative

Plenary Co-Chairs

* David Allstot, Carnegio Mellon Univeristy, USA, [allstot@cmu.edu](mailto:allstot@cmu.edu)
* Yuan Xie, Alibaba T-Head Semiconductor Co. Ltd., USA, [yuanxie@ece.ucsb.edu](mailto:yuanxie@ece.ucsb.edu)
* Zhihua Wang, Tsinghua University, China, [zhihua@tsinghua.edu.cn](mailto:zhihua@tsinghua.edu.cn)

Finance Co-Chair

* Jian Zhao, Shanghai Jiao Tong University, China, [zhaojianycc@sjtu.edu.cn](mailto:zhaojianycc@sjtu.edu.cn)
* Di He, Shanghai Jiao Tong University, China, [dihe@sjtu.edu.cn](mailto:dihe@sjtu.edu.cn)

Special Session Co-Chairs

* Wei-Sheng Zhao, Beihang University, China, [weisheng.zhao@buaa.edu.cn](mailto:weisheng.zhao@buaa.edu.cn)
* Malgorzata Chrzanowska-Jeske, Portland State University, USA, [jeske@ece.pdx.edu](mailto:jeske@ece.pdx.edu)
* One from Europe

Tutorial Co-Chairs

* Li Li, University Science and Technology of China, China, [lil1@ustc.edu.cn](mailto:lil1@ustc.edu.cn)
* Shahriar Mirabbasi, University of British Columbia, Canada, [shahriar@ece.ubc.ca](mailto:shahriar@ece.ubc.ca)
* Patricia Desgreys, Telecom Paris, France, [patricia.desgreys@telecom-paris.fr](mailto:patricia.desgreys@telecom-paris.fr)

Demo Co-Chairs

* Ross Walker, University of Utah, USA, [ross.walker@utah.edu](mailto:ross.walker@utah.edu)
* Philipp Hafliger, University of Oslo, Norway, [hafliger@ifi.uio.no](mailto:hafliger@ifi.uio.no)
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WiCAS and YP Co-Chairs

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* Yongfu Li, Shanghai Jiao Tong University, China, [yongfu.li@sjtu.edu.cn](mailto:yongfu.li@sjtu.edu.cn)
* One from Europe

Industry Advisory and Entrepreneurship Co-Chairs

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* Yongxin Zhu, CAS Shanghai Advanced Research Institute, China

Local Arrangement Co-Chairs

* Yan Liu, Shanghai Jiao Tong University, China, [yan.liu06@sjtu.edu.cn](mailto:yan.liu06@sjtu.edu.cn)